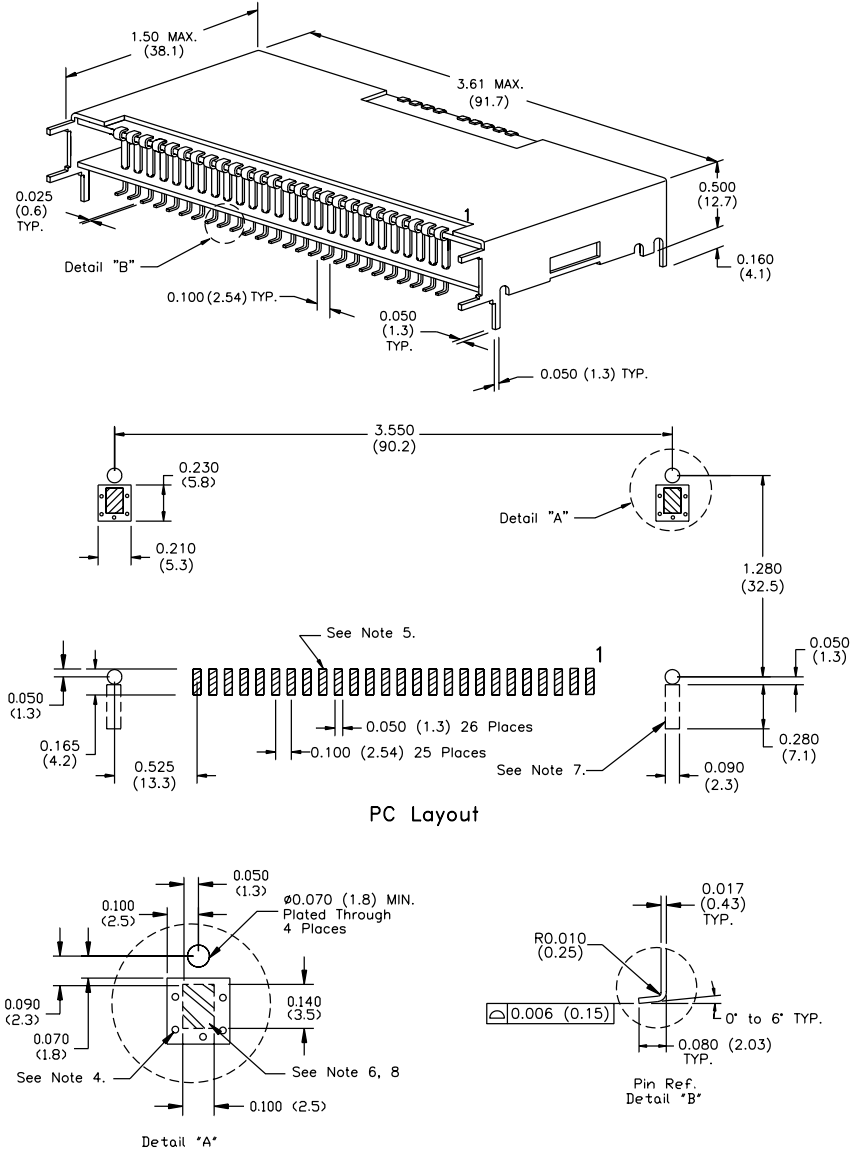


**PACKAGE INFORMATION AND DIMENSIONS**

Horizontal Surface Mount (Suffix C)



**Notes:** (Rev. D)

- 1: All dimensions are in inches (mm).
- 2: 2 place decimals are  $\pm 0.030$  ( $\pm 0.8\text{mm}$ ).
- 3: 3 place decimals are  $\pm 0.010$  ( $\pm 0.3\text{mm}$ ).
- 4: Vias are recommended to improve copper adhesion.
- 5: Power pin connections should utilize two or more vias per input, ground and output pin.
- 6: Solder mask openings to copper island for solder joints to mechanical pins.
- 7: Recommended mechanical keep out area (dotted lines).
- 8: Electrically connected case to secondary ground plane.

**Power Trends proprietary package design.  
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